

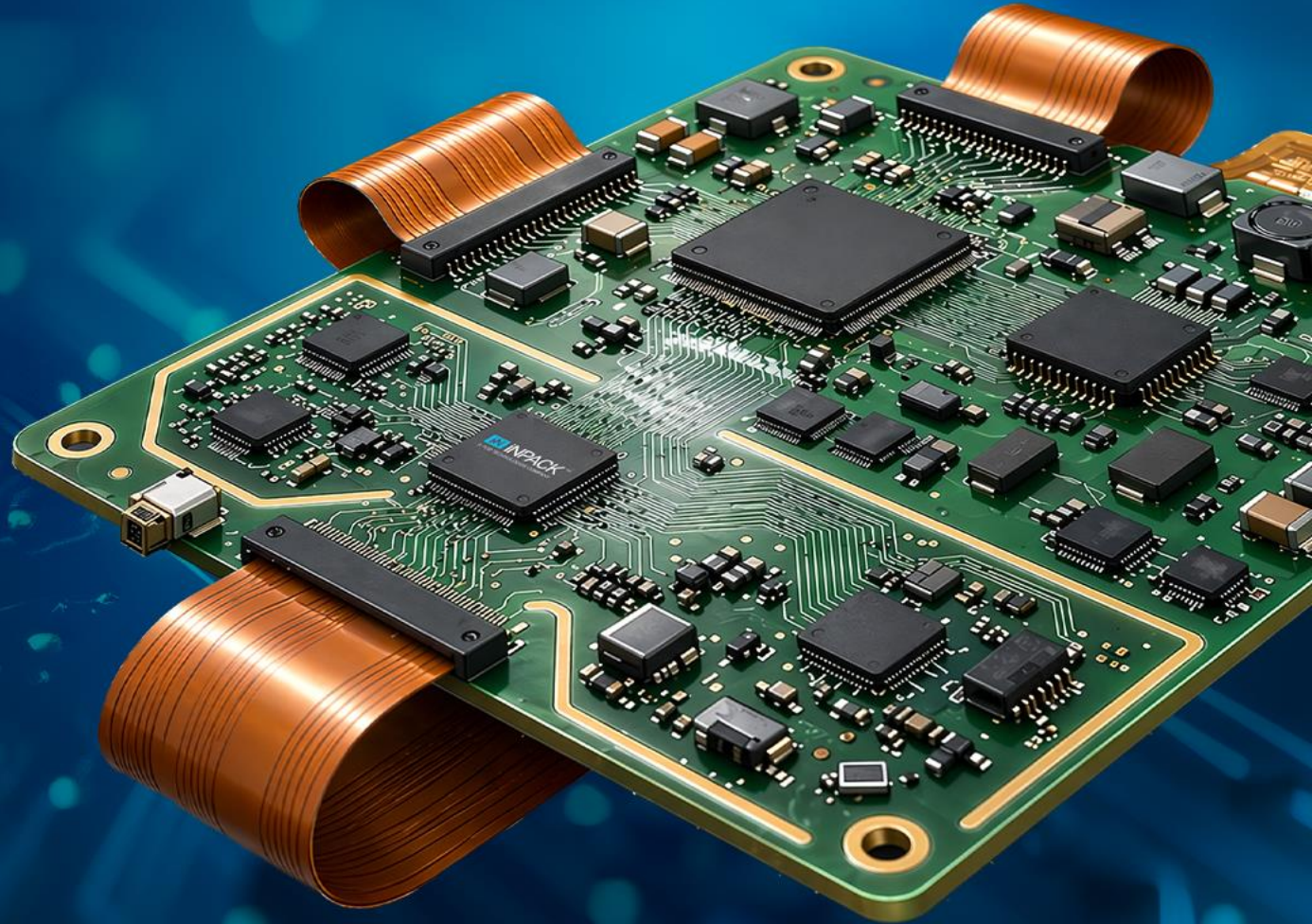


PCB All-in-One Solutions

Q2 2026

Company Presentation

August 2026



Forward looking statement

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Management Organization Chart



Oved Shapira
CEO



Tomer Dvash
CFO & Deputy CEO



Yaniv Maydar
VP R&D and Innovation,
GM INPACK



Yossi Ohayon
VP Head of
Circuits Division



Nir Marko
VP Head of
Assembly Division



Michael Digerman
VP Supply Chain & Trade



Tali Pedhazur-Zuri
VP HR



PCB TECHNOLOGIES At a Glance

Providing All-in-One, Cutting-Edge Hardware Electronics Technology

Legacy

Since 1981
HQ is in Israel
789 Employees

Performance
((Q2-24 > Q2-26)

TTM Revenue – 189 M\$
CAGR Sales TTM : 16.5%
CAGR GP TTM : 32.2%
CAGR EBITDA TTM : 34%

Diversified Customer Base (2025)

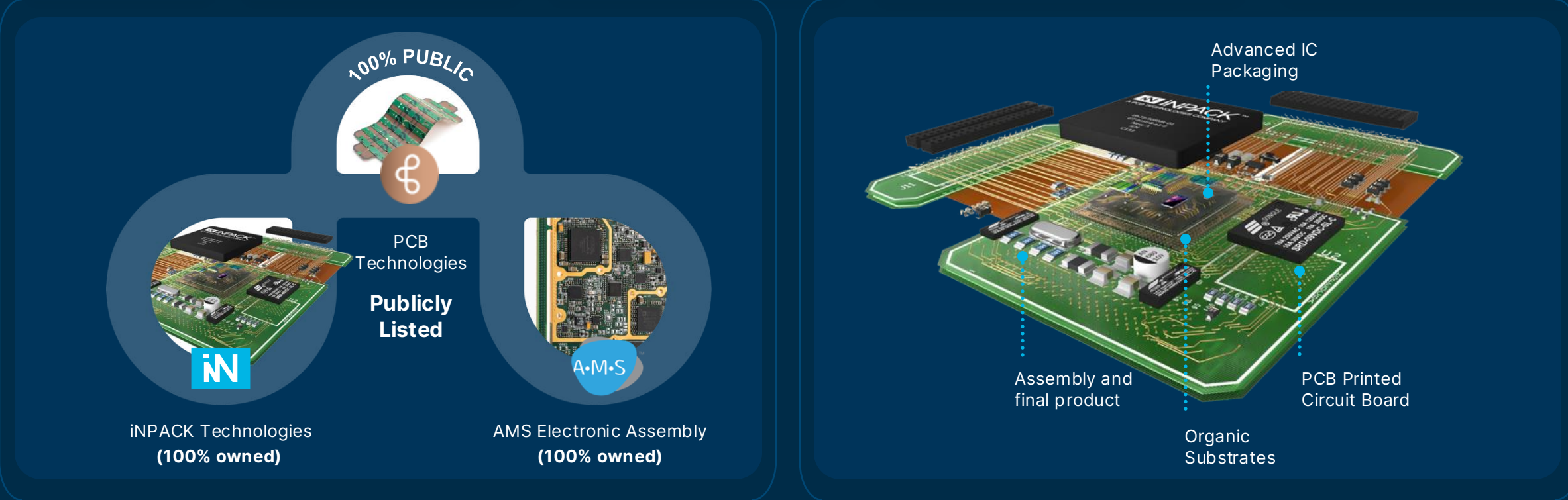
59% Defense and Aerospace
16% Industrial Instruments
25% Medical

Innovation

Strong R&D and Engineering Team
New Products - 25% of Total Revenue
+100 Customers Programs

Value Proposition

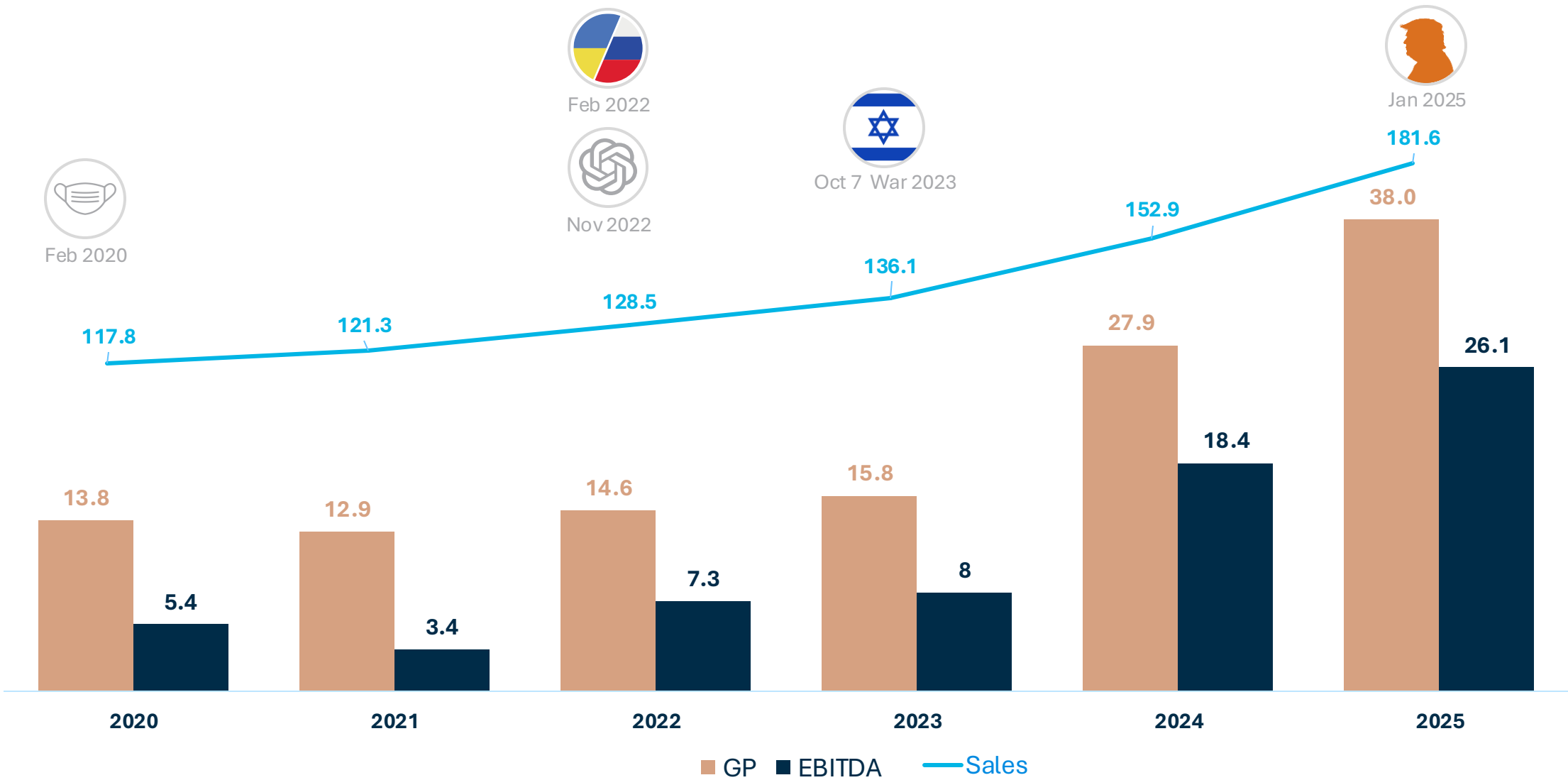
One Site, All-in-One Solution:
Bridging PCB Fabrication,
IC Packaging and Final
Product Integration



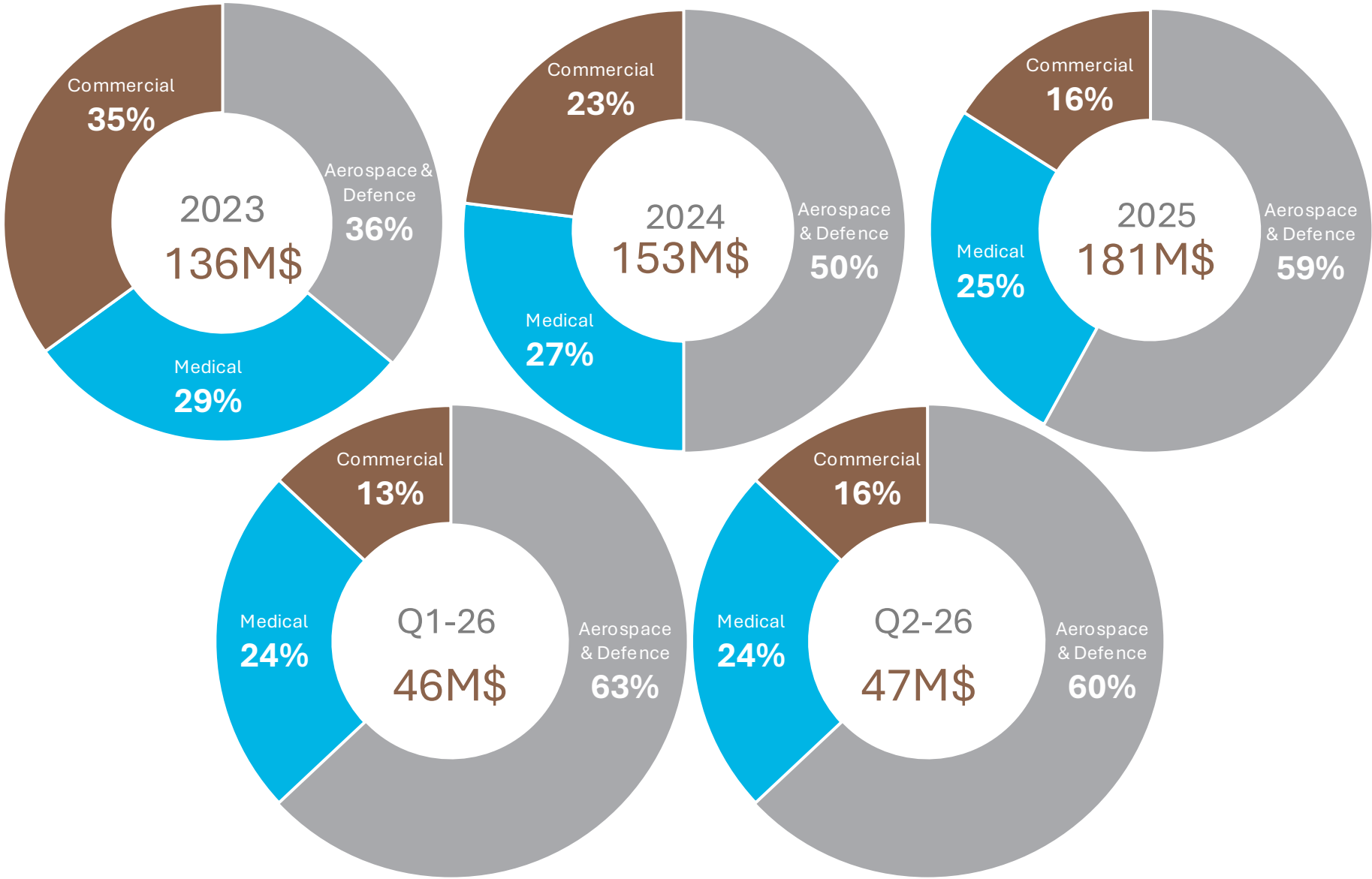
P&L Financial Results 2020-2025

CAGR 2020-2025

— Sales **9.04%** ■ GP **22.4%** ■ EBITDA: **37.2%**



Revenue Mix by Segment



Volume, Mix and Operational Excellence

Over the last five years, **volume has grown superbly, while overhead costs have remained stable to moderate.**

Mix improvement derived from the demand for technology and solutions **results in better direct contribution margins.**

Operational excellence driven **scrap reduction and throughput improvement.**



Technology

Customer Needs

Miniaturization &
ULTRA HDI (Substrate)

Heat dissipation &
thermal management

High-precision &
multi-layer registration

System integration
& ODM solution

Our Investments (Last 5 Years)

Significant CAPEX
investments **43M\$**

Increased R&D
spending **7.5M\$**

Expansion of
engineering headcount

Launch of INPACK's
advanced packaging division.



TM

External and buried Heat Sinks,
Heavy Copper and High-End
thermal conductivity materials

Sequential Lamination

Up to 5 lamination cycles for
increased density

RIGID FLEX

Mixed material build-up /
Book-binde

RIGID

From standard to extreme complexity blind, buried,
stacked, back-drill, and more...

HDI

Allowing ambitious miniaturization by producing
the most dense and accurate lines, spaces and
laser drilled interconnects

FLEX

HDI / thin boards / various
configurations



All-in-One Solution

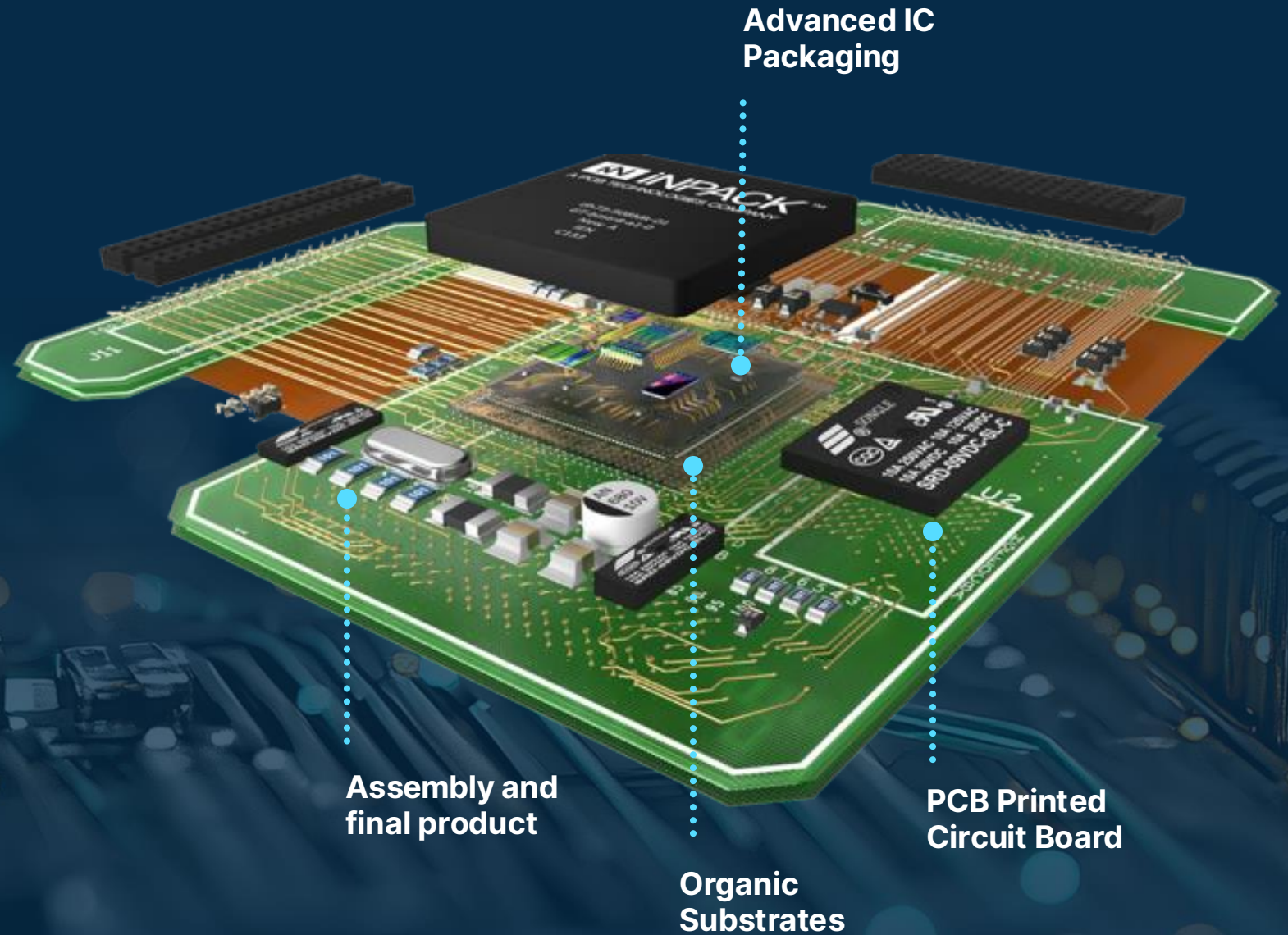
What's in it for us?

Maximize profit potential on every technology vertical

Customer's project time to market value

One-stop shop captivate

Generate revenue from NRE to mass production



Growth Potential, International TAM

Our current annual sales are about **1% of the TAM** in the US and the EU

	Company Share from 2025 Revenue	US+EU Total *EMS Market Size 2024 (B\$)	PCB & Substrate Market Siz (B\$)	IC Packaging Market Size (B\$)	Assembly & Final Product Market Size (B\$)	Company Addressable Market 2024 (B\$)	Segment CAGR % (2025-2030)
Aerospace & Defense	59%	45	5	2	38	7.2	6.1%--8.5%
Medical Technologies	25%	32	3	2	27	3.7	5.8%--6.1%
Industrial Instruments	16%	41	4	2	35	4.7	5.6%--6.3%
Total		118	12	6	100	15.6	

*Electronic Manufacturing Services

Sources: Mordor Intelligence, K.B.V Research



Key Business Highlights



Sales Trend K\$ (TTM)

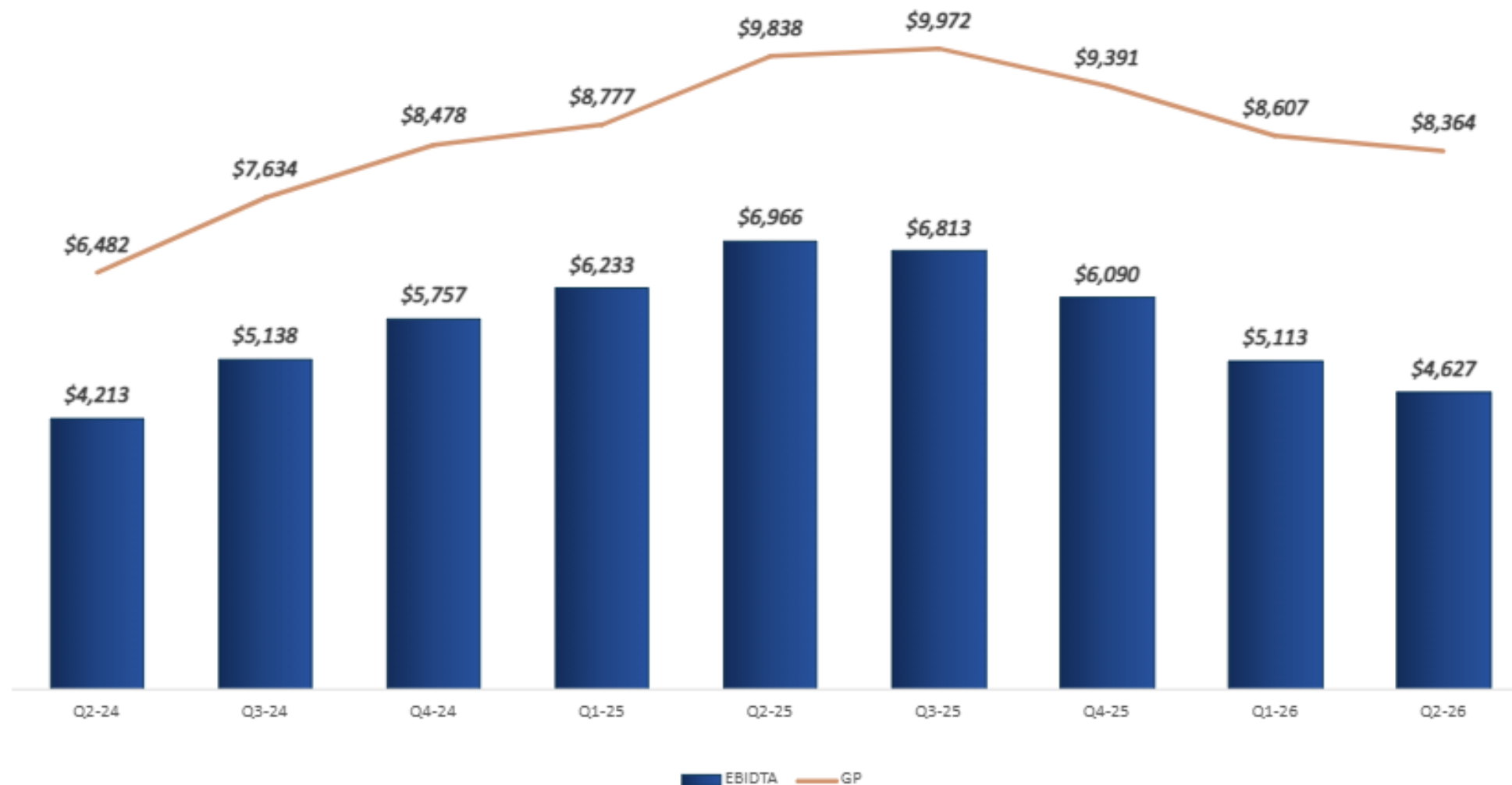
Sales CAGR Q2-24>>Q2-26: 16.5%



Consistent Growth in Sales



Consolidate EBITDA & GP Trends K\$

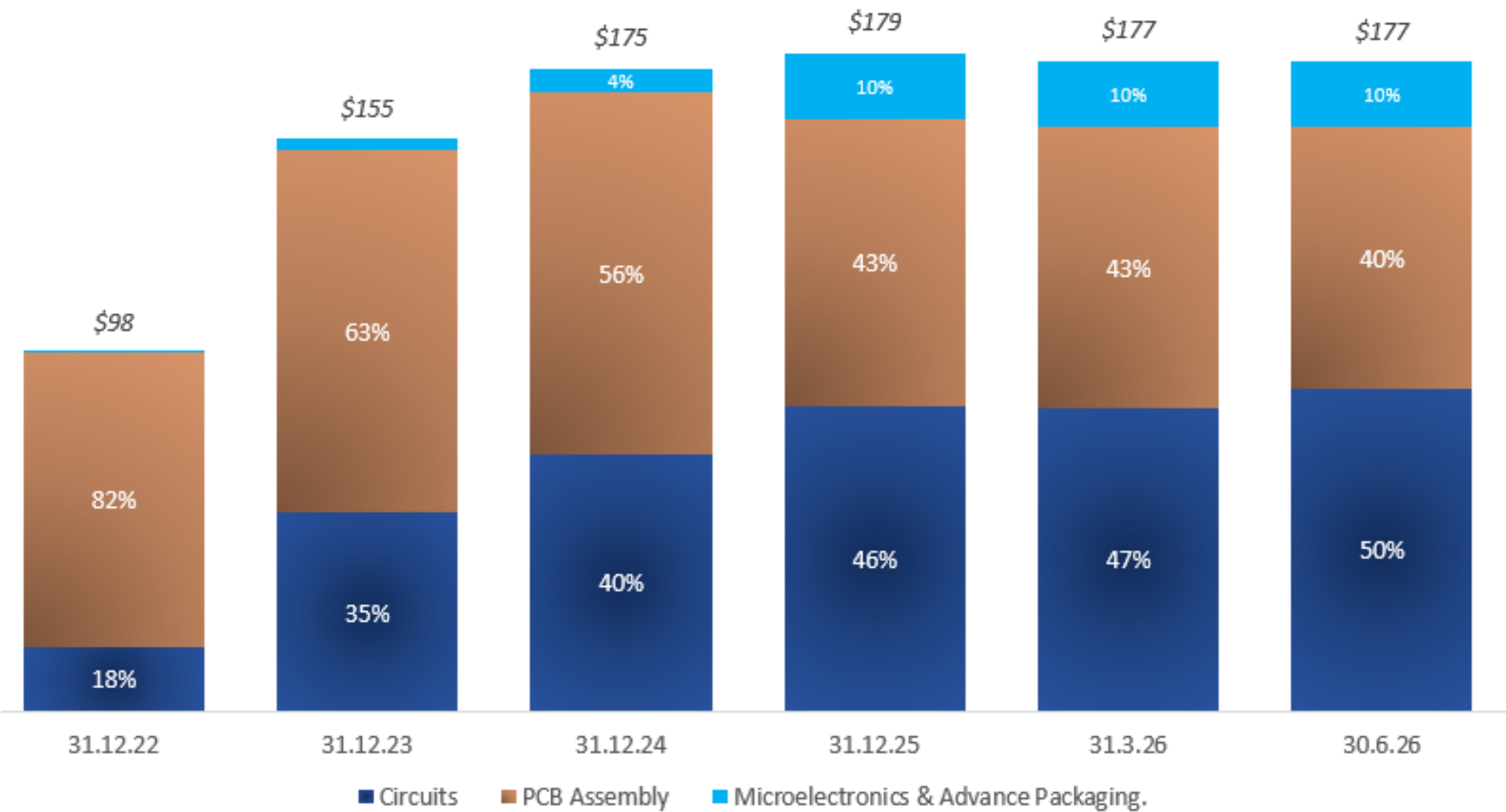


CAGR GP TTM Q2-24 >> Q2-26: 32.2%

CAGR EBITDA TTM Q2-24 >> Q2-26: 34.0%



Backlog & Long Term Agreements (LTA) M\$



Information presented in this chart is based on dates adjacent to the release of the financial statements



What we are going to do in the next years....

Capacity and efficiency

New plating line – PCB

Automation – PCB / Assembly / INPACK

Increase in house capabilities

Capitalize on our process IP

Substrate with ULTRA HDI and more...

SIP and MCM

Increase from ODM services

Materialize the growth opportunity of international TAM.

Establish local operation and commercial team in the US and EU.

Support our PRIME customers' success- FMF and offset.

Diversify Our customer portfolio.



Thank you

